



Material Content Data Sheet



Sales Product Name		BSS169 H6327		Issued		29. August 2013		
MA#		MA000932460						
Package		PG-SOT23-3-5		Weight*		9.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		393	
	noble metal	gold	7440-57-5	0.014	0.15		1524	
	inorganic material	silicon	7440-21-3	0.161	1.73	1.92	17270	19187
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		967	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	copper	7440-50-8	3.000	32.11	32.25	321077	322431
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	788	788
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6112	
	plastics	epoxy resin	-	1.228	13.14		131396	
	inorganic material	silicondioxide	60676-86-0	4.426	47.36	61.11	473637	611145
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16013	16013
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30436	30436
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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